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ABSTRACT

There is provided a method for polishing a semiconductor wafer, in which by using a specific polishing cloth as one for use in a mirror polishing step for the semiconductor wafer, especially in a final polishing stage thereof, generation of micro-scratches and blind scratches on a wafer surface is prevented. In a polishing step of mirror polishing the semiconductor wafer using a polishing cloth, the polishing is performed using the polishing cloth with a nap layer of 500 μm or more in thickness.